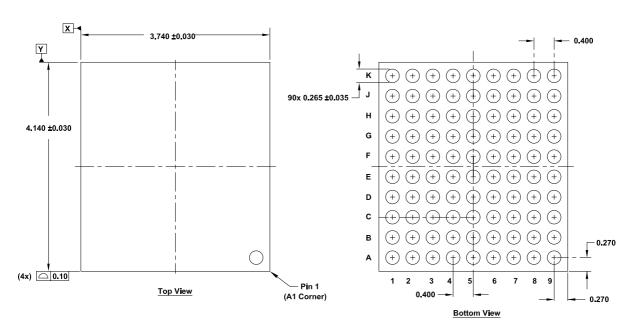
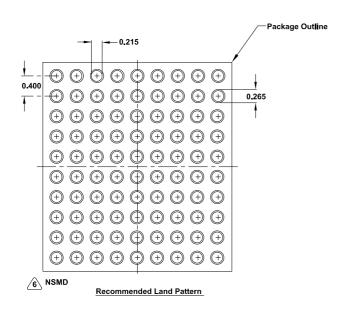
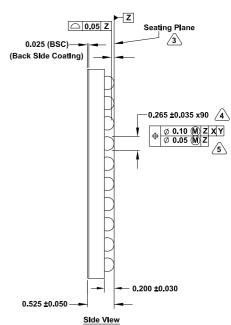
Plastic Packages for Integrated Circuits

Package Outline Drawing

W9x10.90 9x10 Array 90 Balls Wafer Level Chip Scale Package (with 25um BSC) Rev 1, 2/2021







NOTES:

- All dimensions are in millimeters.
- 2. Dimensions and tolerances per ASME Y14.5-1994.
- 3. Primary datum Z and seating plane are defined by the spherical crowns of the bump.
- \triangle Dimension is measured at the maximum bump diameter parallel to primary datum Z.
- 5. Bump position designation per JESD 95-1, SPP-010.
- 6 NSMD refers to non-solder mask defined pad design per TB451.